REPSOL REDEMUL-D
ANIONIC EMULSIONS WITH LOW SOLIDS CONTENT FOR PANELS

Description

Repsol´s REDEMUL®-D series consists of paraffin emulsions with low solids content and small particle size, designed for waterproofing chipboard panels. They are made using a mixture of paraffins, carefully chosen and treated to ensure the best waterproofing results. They have been emulsified with a selection of surfactants capable of ensuring their maximum stability, both in transportation and in handling.

Applications

The REDEMUL®-D range of emulsions was designed to guarantee compliance with our customers´ requirements for all kinds of processes, applications and finishes (chipboard, OSB, MDF, etc.). They are characterised by an excellent water-barrier effect, large coating capacity and stability in handling and storage, whilst providing excellent resistance to hard water.

Packaging

REPSOL REDEMUL ®-D products are supplied in 200-litre drums, 1.000-litre containers and using 25-mt road tankers. They should be stored in a closed container with a venting system and protected from sudden temperature changes in a range between 10 ⁰C and 30 ⁰C

Typical particle size distribution
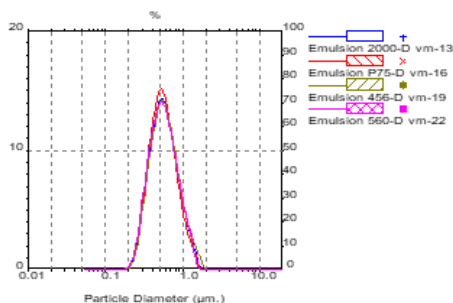
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Technical Characteristics

	Unity	Method	456-D	560-D	P-75D	2000-D
Colour	-	IT PAL-100	B	B	B	B
Brookfield Viscosity	cP	IT PAL-101	<100	<600	<500	<200
Solids	%p	IT PAL-104	43-47	49-51	48-52	49-51
pH	-	IT LAB-100	9	9	9	9
Average particle size	µm	IT LAB-312	0,6	0,6	0,6	0,6
Mechanical stability	-	IT PAL-102	E(1)	E(1)	E(1)	E(1)
Stability with hard water	-	IT PAL-103	E(1)	E(1)	E(1)	E(1)
Density at 25 ºC	g/ml	ASTMD1298	0,950	0,950	0,950	0,950
E(1): Stable						

Unless otherwise indicated, the values presented in the technical data should be considered as typical values.